



Data Sheet

Customer:

Part No:

CL-BITZ1608DLG-02

Sample No:

Description:

Item No:

Customer			
Check	Inspection	Approval	Date

SMD·CHIP



Features

- . 0603 package
- . Top view LED
- . Compatible with infrared and vapor phase reflow solder process.
- . Wide viewing angle
- . Pb-free
- . RoHS compliant

Description

192 package has high efficacy ,high power consumption ,wide viewing angle and a Compact form factor . The features make this package an ideal LED for all lighting applications

Applications

- . General lighting
- . Decorative and Entertainment Lighting
- . Indicators
- . Automotive Telecommunication
- . Switch lights

Device Selection Guide

Chip Material	Emitted Color	Resin Color
InGaN	Green	Water Clear

Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Rating	Unit
Continuous Forward Current	I _F	30	mA
Operating Temperature	T _{opr}	-40 ~ +85	°C
Storage Temperature	T _{stg}	-40 ~ +100	°C
Peak Forward Current (T=1.3s, tp=0.3s)	I _{FP}	120	mA
Soldering Temperature*1	T _{sol}	Reflow Soldering : 260 °C Hand Soldering : 350 °C	for 10 sec. for 3 sec.
Power Dissipation at(or below) 25°C Free Air Temperature	P _d	115	mW
Electrostatic Discharge(HBM)	ESD	1000	V

Notes: *1: Soldering time ≦ 5 seconds.

Electro-Optical Characteristics (Ta=25°C)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Condition
Forward Voltage	V _F	2.7	---	3.1	V	I _F =5mA
Dominant Wavelength	λ _d	515	----	535	nm	I _F =5mA
Reverse Current	I _R	---	---	10	μA	V _R =5V
Luminous Intensity	I _v	72	140	225	mcd	I _F =5mA
Viewing Angle	2θ _{1/2}	---	130	---	deg	I _F =5mA

Notes:

1. Tolerance of Luminous Intensity ±10%.
2. Tolerance of Forward Voltage : ±0.05V.

Bin Range of Luminous Flux

Bin Code	Min	Max	Unit	Condition
AQ1	72	90	mcd	I _F =5mA
AQ2	90	112		
AR1	112	140		
AR2	140	180		
AS1	180	225		

Note:

Tolerance of Luminous Flux: $\pm 10\%$.

Bin Range of Forward Voltage

Bin Code	Min	Max	Unit	Condition
27	2.70	2.80	V	I _F =5mA
28	2.80	2.90		
29	2.90	3.00		
30	3.00	3.10		

Note:

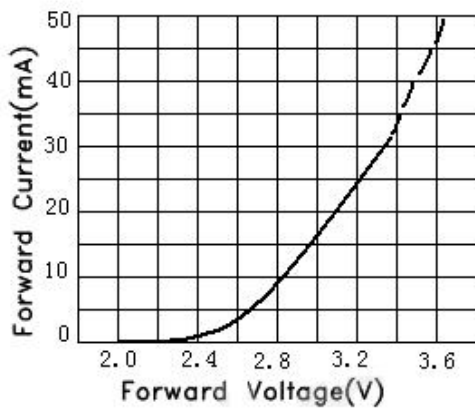
Tolerance of Forward Voltage: $\pm 0.1V$.

Bin Range of Dominant Wavelength

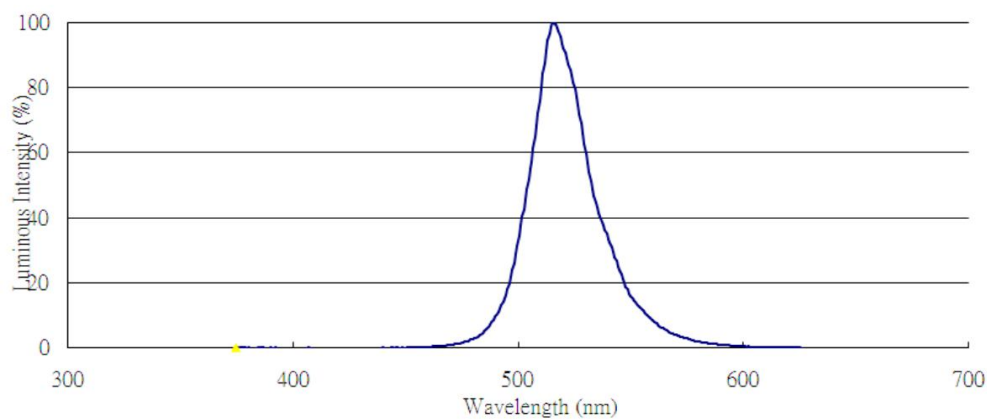
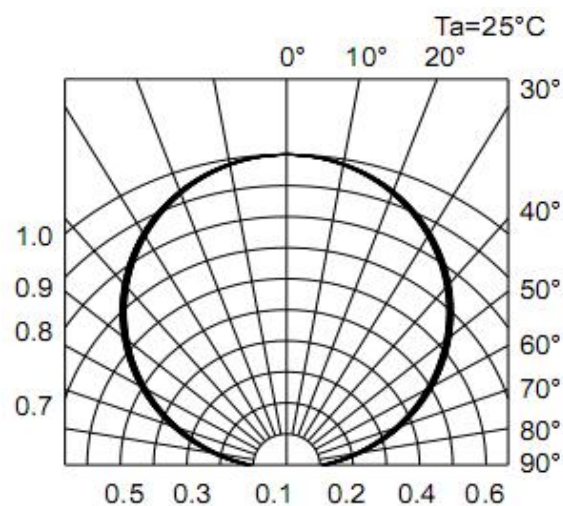
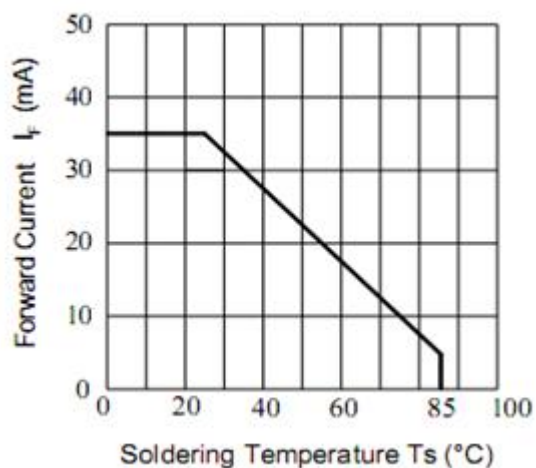
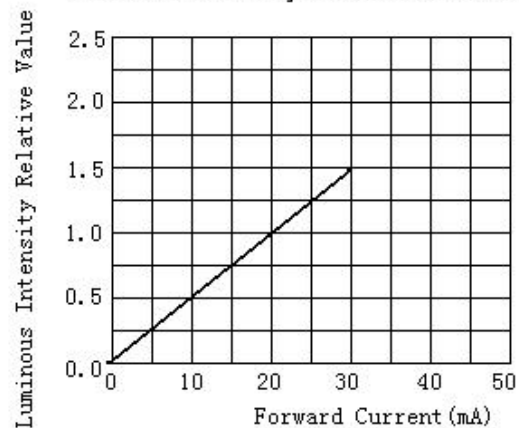
Bin Code	Min	Max	Unit	Condition
51c	515.0	517.5	nm	I _F =5mA
51d	517.5	520.0		
52a	520.0	522.5		
52b	522.5	525.0		
52c	525.0	527.5		
52d	527.5	530.0		

Typical Electrical/Optical/Characteristics Curves for IR

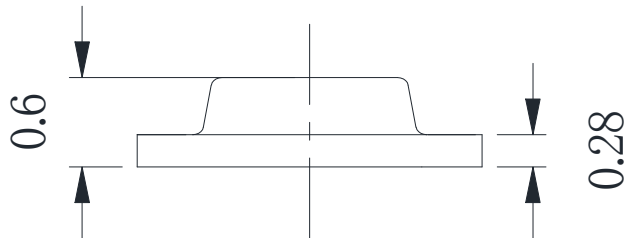
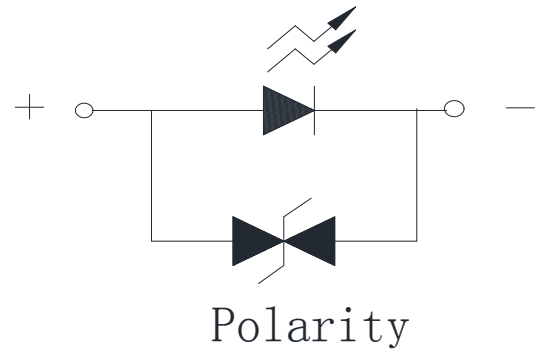
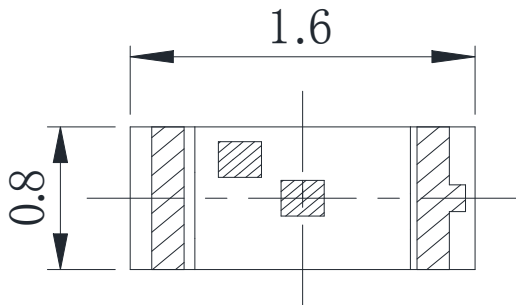
Forward current Vs. Forward voltage



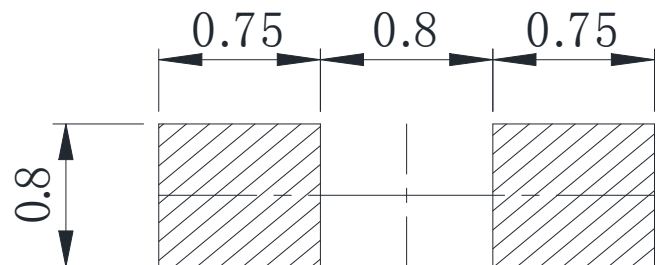
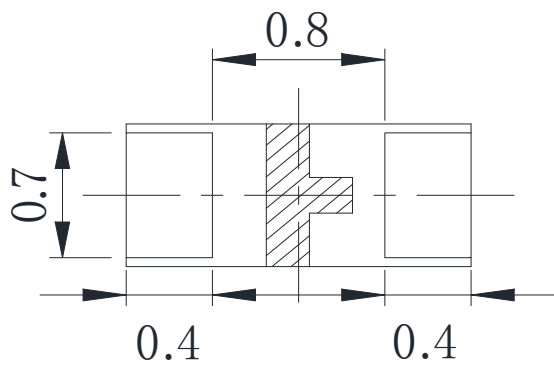
Luminous Intensity Vs. Forward Current



Package Dimensions



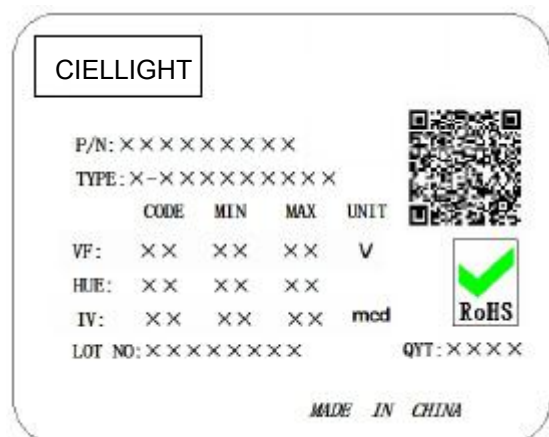
Recommended Solder Pad



Note:

Tolerance unless mentioned is ± 0.1 mm, Unit = mm.

Label Form Specification



CPN: Customer's Production Number

P/N : Production Number

QTY: Packing Quantity

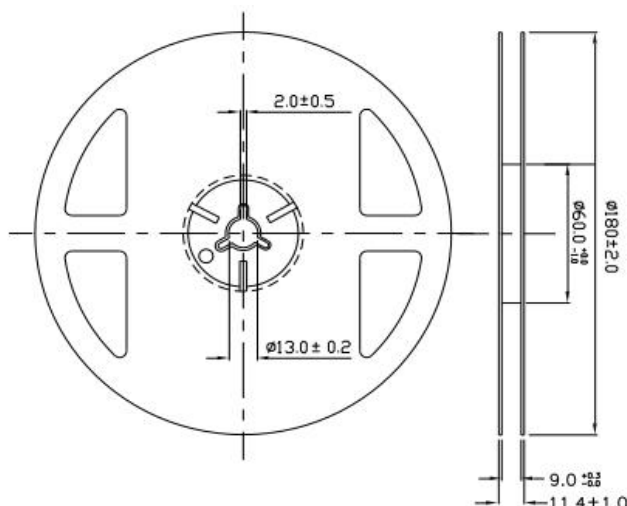
CAT: Ranks

HUE: Peak Wavelength

REF: Reference

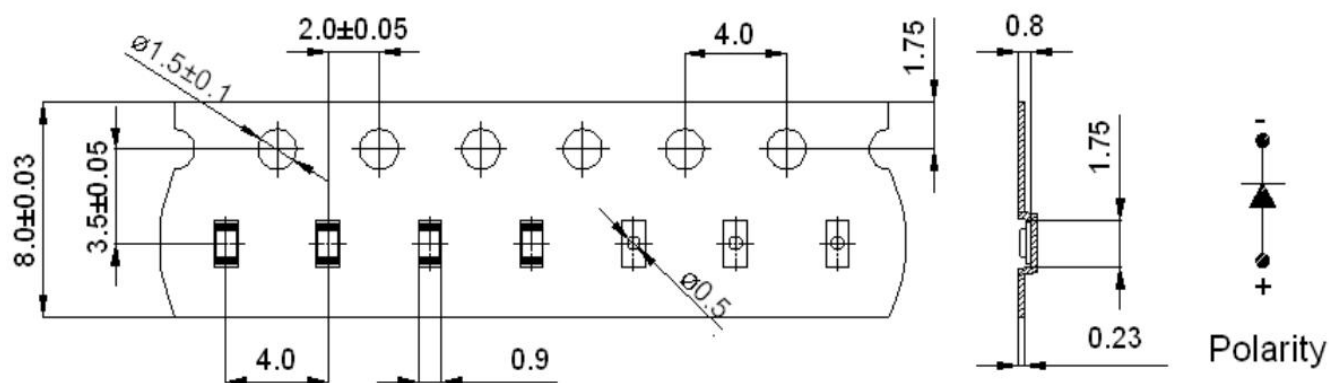
LOT No: Lot Number

Reel Dimensions



Note: The tolerances unless mentioned is $\pm 0.1\text{mm}$,Unit = mm

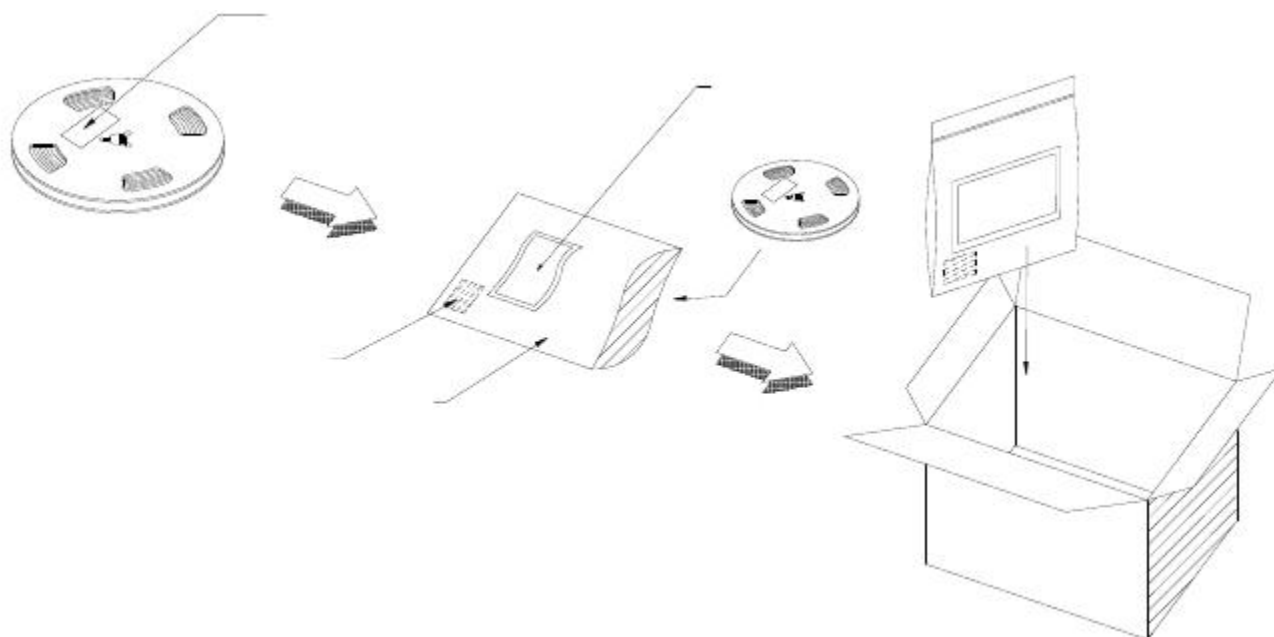
Carrier Tape Dimensions:(Quantity: 4000pcs/reel)



Note:

- 1.Tolerance unless mentioned is $\pm 0.1\text{mm}$,Unit = mm.
2.Minimum packing amount is 1000/2000 pcs per reel.

Moisture Resistant Packing Process



Reliability Test Items and Conditions

The reliability of products shall be satisfied with items listed below.

Confidence level : 90%

LTPD : 10%

No.	Items	Test Condition	Test Hours/Cycles	Sample Size	Ac/Re
1	Reflow Soldering	Temp. : 260°C/10sec.	6 Min	22 PCS	0/1
2	Thermal Shock	H : +100°C 5min ∫ 10 sec L : -10°C 5min	300 Cycles	22 PCS	0/1
3	Temperature Cycle	H : +100°C 15min ∫ 5 min L : -40°C 15min	300 Cycles	22 PCS	0/1
4	High Temperature/Humidity Reverse Bias	Ta=85°C, 85%RH	1000 Hrs.	22 PCS	0/1
5	Low Temperature Storage	Ta=-40°C	1000 Hrs.	22 PCS	0/1
6	High Temperature Storage	Ta=100°C	1000 Hrs.	22 PCS	0/1
7	DC Operation Life	Ta=25°C IF = 20 mA	1000 Hrs.	22 PCS	0/1

Precautions For Use

1. Over-current-proof

Customer must apply resistors for protection , otherwise slight voltage shift will cause big current change (Burn out will happen).

2. Storage

2.1 Do not open moisture proof bag before the products are ready to use.

2.2 Before opening the package, the LEDs should be kept at 40°C or less and 90%RH or less.

2.3 The LEDs should be used within a year.

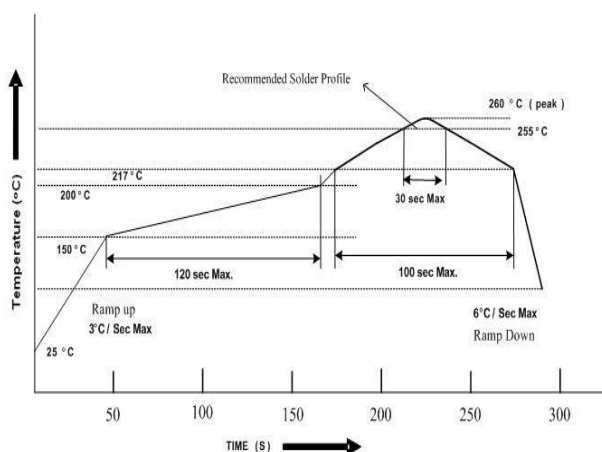
2.4 After opening the package, the LEDs should be kept at 30°C or less and 60%RH or less.

2.5 The LEDs should be used within 168 hours (7 days) after opening the package

2.6 If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the following J-STD-33 Standard.

3. Soldering Condition

3.1 Pb-free solder temperature profile



3.2 Reflow soldering should not be done more than two times.

3.3 When soldering, do not put stress on the LEDs during heating.

3.4 After soldering, do not warp the circuit board.

4. Soldering Iron

Each terminal is to go to the tip of soldering iron temperature less than 350°C for 3 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.

5. Repairing

Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.